

Accepted Manuscript

Interfacial reactions at the joints of CoSb₃-based thermoelectric devices

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PII: S0925-8388(16)34315-8

DOI: [10.1016/j.jallcom.2016.12.386](https://doi.org/10.1016/j.jallcom.2016.12.386)

Reference: JALCOM 40309

To appear in: *Journal of Alloys and Compounds*

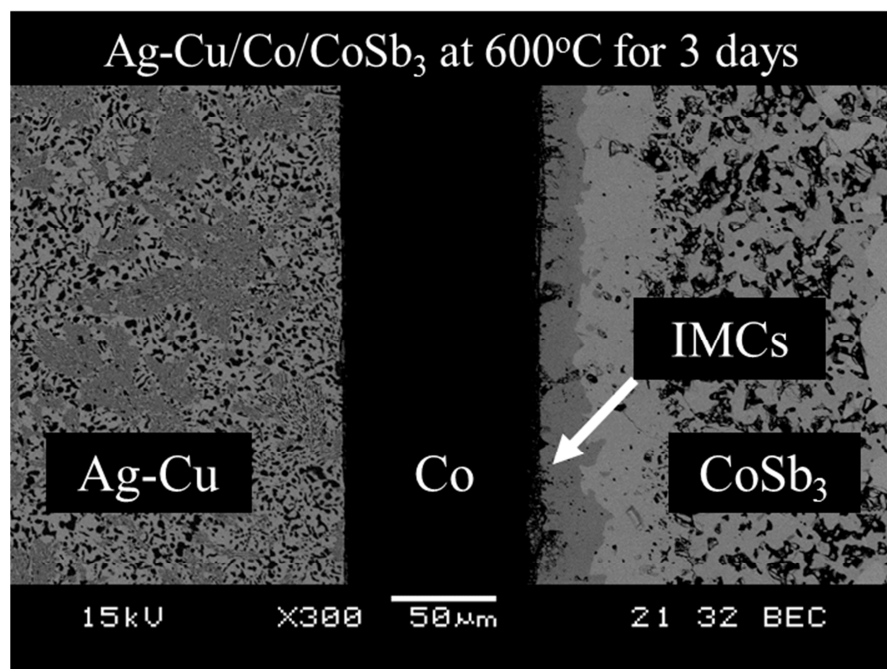
Received Date: 8 October 2016

Revised Date: 23 November 2016

Accepted Date: 28 December 2016

Please cite this article as: S.-w. Chen, A.H. Chu, D.S.-H. Wong, Interfacial reactions at the joints of CoSb₃-based thermoelectric devices, *Journal of Alloys and Compounds* (2017), doi: 10.1016/j.jallcom.2016.12.386.

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